

Appl. No. 10/657,415
Amdt. Dated 11/21/2005
Reply to Final Office Action of 10/28/2005

REMARKS

Claims 17-20, 24-32, 36-37 and 41-49 are pending in the present application. Claims 20-23, 33-35 and 38-40 have been cancelled without prejudice. Claims 41-49 have been added.

This Amendment is in response to the Final Office Action mailed October 28, 2005. In the Final Office Action, the Examiner continued to rejected claims 17-20, 31, 32, 36, and 37 under 35 U.S.C. §102(e). Applicants have amended claims 17, 31 and 36. Reconsideration in light of the amendments and remarks made herein is respectfully requested.

Rejection Under 35 U.S.C. § 102

In the Office Action, the Examiner rejected claims 17-20, 31, 32, 36, and 37 under 35 U.S.C. §102(e) as being anticipated by Lau (U.S. Patent No. 5,825,084). Based on the amendments set forth in claims 17, 31 and 36, Applicants respectfully traverse the rejection and contend that the Examiner has not met the burden of establishing a *prima facie* case of anticipation.

As the Examiner is aware, to anticipate a claim, the reference must teach every element of the claim. "A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference." Vergegaal Bros. v. Union Oil Co. of California, 814 F.2d 628, 631, 2 USPQ 2d 1051, 1053 (Fed. Cir. 1987). "The identical invention must be shown in as complete detail as is contained in the...claim." Richardson v. Suzuki Motor Co., 868 F.2d 1226, 1236, 9 USPQ 2d 1913, 1920 (Fed. Cir. 1989).

For instance, with respect to independent claim 17, *inter alia*, Applicants respectfully submit that Lau does not disclose the operations of (1) forming a first conductive strip along the first edge of the first bond shelf and (2) forming a second conductive strip along the first edge of the first bond shelf. The first conductive strip wraps around and over the first edge of the first bond shelf to electrically couple a first bonding pad of the first plurality of bonding pads on the first bond shelf to a first power bus under the first bond shelf. The second conductive strip wraps around and over the first edge of the first bond shelf to electrically couple a second bonding pad

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of the first plurality of bonding pads on the first bond shelf to a second power bus under the first bond shelf.

With respect to independent claim 31, *inter alia*, Applicants respectfully submit that Lau does not disclose the operation of removing a second portion of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf. A first conductive strip of the pair of conductive strips is coupled to a first bonding pad of the plurality of bonding pads coupled to a first power bus having a first voltage level. A second conductive strip of the pair of conductive strips is coupled to a second bonding pad of the plurality of bonding pads coupled to a second power bus having a second voltage level less than the first voltage level.

With respect to independent claim 36, *inter alia*, Applicants respectfully submit that Lau does not disclose the operation of removing a second portion of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf. A first conductive strip of the conductive material is coupled to both a first bonding pad of the plurality of bonding pads and a first power bus having a first voltage level. Similarly, a second conductive strip of the conductive material is coupled to both a second bonding pad of the plurality of bonding pads and a second power bus having a second voltage level less than the first voltage level.

Therefore, Applicants believe that independent claims 17, 31, 36, and their respective dependent claims are distinguishable over the cited prior art reference. Accordingly, Applicants respectfully request withdrawal of the rejection under 35 U.S.C. §102(c).

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Conclusion

Applicants respectfully request that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

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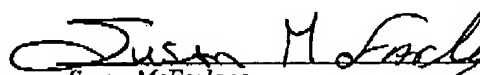
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